



**GOFORD SEMICONDUCTOR CO., LTD.**  
**Reliability Test Report**

Part Number: MOSFET SMD Series

Yearly Reliability monitoring: 2023

Based on similar Structural

Test Results: PASS

Test Items		MSL3 , TCT, PCT, THT, HTST, SD, HTRB, HTGB.			
Test No.	Test item	Test Condition	Test Standard	Qty (pcs)	Rej/ Acc
1	MSL3 Preconditioning	BAKE:125±5°C , 24H Soak:30°C60%RH , 192H Reflow: 260°C 3 Times	JESD22-A113	190	0/1
2	TCT Temperature Cycle Test	-65°C-150°C ,200cycle	JESD22-A104	45	0/1
3	PCT Pressure Cooker Test	T=121°C, RH=100% , PA =2atm,48H	JESD22-A102	45	0/1
4	THT Temperature & Humidity Test	85°C , 85%RH /500H	JESD22-A101	45	0/1
5	HTST High Temperature Storage Test	150°C /500H	JESD22-A103	45	0/1
6	SD Solderability	245±5°C /10±1S	J-STD-002	10	0/1
7	HTRB	Tj=150°C,Bias= 80%VDS, 168H/500H/1000H	JESD22-A108	77	0/1
8	HTGB	Tj= 150°C, Bias=100%VGS, 168H/500H/1000H	JESD22 -A108	77	0/1